

UHMWPE POROUS MATERIAL
SUNMAP LC

Features

- As SUNMAP is a porous sintered material having an open-cell structure; it offers the excellent air and moisture permeability.
- As SUNMAP is made of porous UHMWPE having high wear resistance and low friction coefficient the slip properties of SUNMAP is enhanced.
- SUNMAP offers good chemical resistance against typical acids and alkalis.
- Base Grade

Structure



Fig. 1

Properties

Table 1. General Properties

Item	Unit	Characteristic value						Test method
		0.1	0.2	0.3	0.5	1.0	2.0	
Thickness	mm	0.1	0.2	0.3	0.5	1.0	2.0	—
Air permeability	cm ³ /cm ² /sec	21	8	7	1.4	0.5	0.2	JIS L1096
Pore size	μm	17						—
Porosity	%	30						—
Tensile strength	MPa	12						JIS C2107
Elongation	%	90						JIS C2107
Hardness	Shore D	48						ASTM D2240
Surface Roughness (Ra)	μm	2.0						JIS B 0601
Coefficient of kinetic friction	—	0.1						JIS K7125
Surface resistance	Ω/□	>10 ¹³						JIS K7194

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LC_03E
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Product size

Table 2 Sheet type

Thickness (mm)	Width (mm)	Length (mm)
0.1	100~700	100~1200
0.2		
0.3		
0.5		
1.0	100~500	100~500
2.0		

Table 3 Roll type

Thickness (mm)	Width (mm)	Length (m)
0.1	100~700	10
0.2		
0.3		
0.5		

Applications

- In ceramic condenser manufacturing process, SUNMAP is used as “shock-absorber”.
- In LCD manufacturing process, SUNMAP is used as “shock-absorber”.

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